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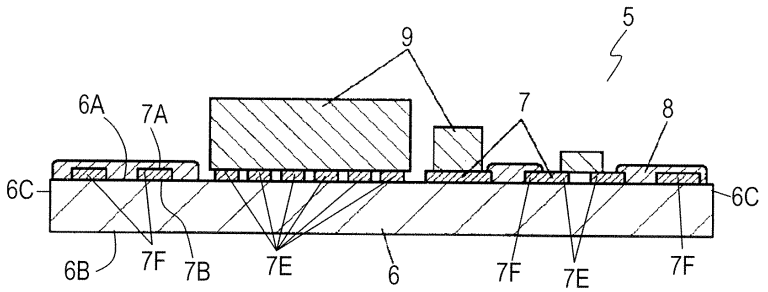
(54) **WIRING BOARD**

(57) A wiring board includes an insulating board having a top surface arranged to have an electronic component mounted thereto, a conductor pattern formed on the top surface of the insulating board, and a heat emitting layer made of heat-emitting material covering the conductor pattern. The heat-emitting material has an emissivity not less than 0.8 for an electromagnetic wave having a wavelength $\lambda = 0.002898/T$ at a temperature T ranging from 293K to 473K. This wiring board suppresses the temperature rise of the electronic component.

Fig. 1



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